Standard Solder Paste Reflow Profile for Kester Paste Containing Alloys: Sn63Pb37 or Sn62Pb36Ag02

- Pre-heating Zone (2.0-4.0 min. max.)
- Soaking Zone (2.0 min. max.) 60-90 sec. typical
- Reflow Zone (45-75 sec. max.) 60 sec. typical
- Cool Down

Temperature (°C):
- Peak Temp. 208 - 230°C
- <2.5 °C/Sec

Time (sec.):
- 0 30 60 90 120 150 180 210 240 270 300

Graph showing the temperature profile over time.